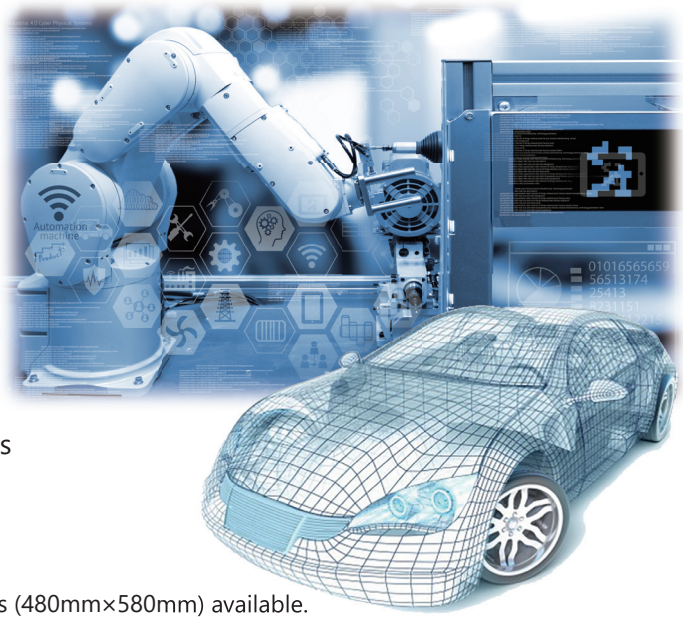
Large Current, High Heat dissipation PCBs

PCB Solutions for Power Electronics Equipment
such as Automotive ECU/PCUs and Industrial Robots



Heat-Resistant Material

High heat resistance requirements increasing with the product miniaturization.

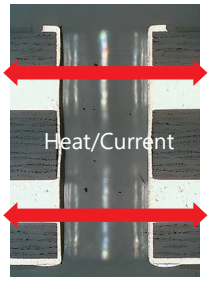
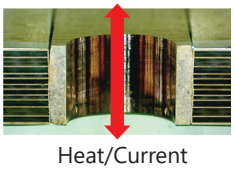
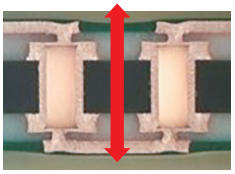
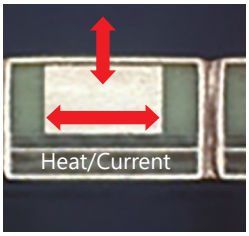
- Improvement of material heat resistance:
  PCBs with materials supporting over Tg=200C°.
  (Tg: Glass transition temperature)
- Selection of materials according to the PCB requirements:
  Wide selection of reliable materials.

Large Current, High Heat dissipation

Optimal technologies to meet our customers various needs such as Large Current and High thermal conductivity.

- No conductor exposure at the edge of the PCB.
- PCB manufactured with conventional materials.
- Product size: Small Semiconductor Packages up to large size PCBs (480mm×580mm) available.
- High thermal conductivity material for high heat dissipation to spread the heat from the hot spots of the PCB.

Solutions for Automotive and Industrial Power Electronic

PCB Technology (General Spec.)	① Thick Cu PCB (Inner layer Cu thickness[μm]: 175, 300, 500, 1000)	② Cu Coin PCB (Cu Coin Shape[mm]: ϕ3.0 ~ϕ8.0, Rectangle)	③ High Thermal Conductivity Material	① + ③ Case Study
Heat Dissipation Path	Horizontal	Vertical	Vertical	Horizontal and Vertical
Current Path	Horizontal	(Vertical)	—	Horizontal
X-section	Thick Cu: 500μm×2 	Copper Coin: Rectangular  Copper Coin Cross Section  Heat/Current	High thermal conductive resin  Thermal Conductivity 2.0 to 3.2W/mK	Thick Cu + High thermal conductive resin 

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